

ABSTRACT

A composition for removing a residue from a wiring board containing an oxidizing agent and an azole compound and having a pH of from 1 to 7 and a cleaning method of a wiring board for removing a residue after dry etching by using this composition are provided. By using the composition for removing a residue of the present invention, in manufacturing a wiring board, residues remaining after dry etching which are derived from a resist or metals can be effectively removed without corroding titanium or titanium alloys with high corrosiveness. In particular, a semiconductor device using a wiring board containing titanium or titanium alloys can be efficiently manufactured.